

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takashi NAKAMURA</td> <td>07/06/2012</td> </tr> <tr> <td>Kosuke YAYAMA</td> <td>07/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Takashi NAKAMURA	07/06/2012	Kosuke YAYAMA	07/06/2012
Name	Execution Date						
Takashi NAKAMURA	07/06/2012						
Kosuke YAYAMA	07/06/2012						
RECEIVING PARTY DATA							
Name:	RENESAS ELECTRONICS CORPORATION						
Street Address:	1753, Shimonumabe, Nakahara-ku, Kawasaki-shi						
City:	Kanagawa						
State/Country:	JAPAN						
Postal Code:	211-8668						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13579766</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13579766		
Property Type	Number						
Application Number:	13579766						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	John R. Mattingly						
Total Attachments: 1 source=8472-Assign#page1.tif							

CH \$40.00 13579766

ASSIGNMENT  
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Takashi Nakamura (Takashi NAKAMURA)

July. 6. 2012

2) Kosuke Yayama (Kosuke YAYAMA)

July, 6, 2012

3) \_\_\_\_\_

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4) \_\_\_\_\_

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5) \_\_\_\_\_

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6) \_\_\_\_\_

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